

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT7043847

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
ZVI OR-BACH	11/27/2021
BRIAN CRONQUIST	11/28/2021
DEEPAK SEKAR	11/28/2021
RECEIVING PARTY DATA	
Name:	MONOLITHIC 3D INC.
Street Address:	1662 COVE POINT RD
City:	KLAMATH FALLS
State/Country:	OREGON
Postal Code:	97601
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	17536097
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	4088399533
Email:	Brian@Monolithic3D.com
Correspondent Name:	BRIAN CRONQUIST
Address Line 1:	1662 COVE POINT RD
Address Line 4:	KLAMATH FALLS, OREGON 97601
ATTORNEY DOCKET NUMBER:	MONOLITHIC3D-15HB1CON1
NAME OF SUBMITTER:	BRIAN CRONQUIST
SIGNATURE:	/Brian Cronquist/
DATE SIGNED:	11/29/2021
Total Attachments: 3	
source=Monolithic3D-15HB1con1_Assignment_Zvi signed#page1.tif	
source=Monolithic3D-15HB1con1_Assignment_Deepak signed#page1.tif	
source=Monolithic3D-15HB1con1_Assignment_Brian signed#page1.tif	

ASSIGNMENT

Whereas, I, **Zvi Or-Bach (hereinafter referred to as Assignor(s)), residing in Haifa, Israel;** have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE
WITH HIGH-K METAL GATE TRANSISTORS**

as described in U.S. Patent Application Serial No. 17/tbd and filed on about November 28, 2021; and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 11 / 27 / 2021

(**Zvi**

Or-Bach)

First Name

Middle Initial

Last Name

20-11-2021

PATENT

ASSIGNMENT

Whereas, I, **Deepak Sekar (hereinafter referred to as Assignor(s)), residing in Sunnyvale, California;** have made a certain invention, and executed United States Patent Application entitled:

A 3D SEMICONDUCTOR DEVICE AND STRUCTURE WITH HIGH-K METAL GATE TRANSISTORS

as described in U.S. Patent Application Serial No. 17/tbd and filed on about November 28, 2021;
and

Whereas, MonolithIC 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

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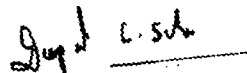
Signed and Sealed:

INVENTOR:

DATE on 11 / 28 / 2021

(**Deepak**

First Name



Middle Initial

Sekar)

Last Name

PATENT

ASSIGNMENT

Whereas, I, **Brian Cronquist** (hereinafter referred to as Assignor(s)), residing in **Klamath Falls, Oregon**; have made a certain invention, and executed United States Patent Application entitled:

**A 3D SEMICONDUCTOR DEVICE AND STRUCTURE
WITH HIGH-K METAL GATE TRANSISTORS**

as described in U.S. Patent Application Serial No. 17/1bd and filed on about November 28, 2021; and

Whereas, Monolithic 3D™ Inc., a company located at 1662 Cove Point Road, Klamath Falls, OR 97601-9300 (hereinafter called "Assignee"), desires to acquire the entire right, title, and interest in the application and the invention, and to any applications, patents and/or utility model registrations filed or obtained therefor in every Country (hereinafter called the "Designated Countries").

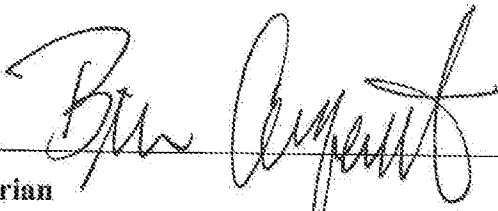
Now therefore, for valuable consideration, receipt of which is hereby acknowledged,

I/we, the above named Assignor(s), hereby sell, assign and transfer to the above named Assignee the entire right, title and interest to file and/or obtain any applications, patents and/or utility model registrations in the Designated Countries as regards the United States application and the invention disclosed therein (including rights of priority based on the United States application), and I/we will execute without further consideration all papers deemed necessary by the Assignee in connection with such applications, patents and/or utility model registrations in the Designated Countries when called upon to do so by the Assignee.

Signed and Sealed:

INVENTOR:

DATE on 28 Nov 2021



 (Brian Cronquist)
 First Name Middle Initial Last Name